Resistors



Metal Glaze™ General Purpose Surface Mount Power Resistor

MM Series

- Up to 2 watts
- Up to 1000 volts
- 0.1 ohm to 2.2 megohm range
- 150°C maximum operating temperature

OBSOLETE



All Pb-free parts comply with EU Directive 2011/65/EU amended by (EU) 2015/863 (RoHS3)

Electrical Data

Size Code	Industry Footprint	IRC Type	Maximum Power Rating	Working Voltage	Resistance Range (ohms)²	Tolerance (+%) ³	TCR (ppm/°C)³	Product Category
В	1206	MMA0204	1/2	400	0.1 to 0.99	1, 2, 5	100	Low Range
					1.0 to 1.0M	1, 2, 5	50, 100	Standard
					20 to 348K	0.25, 0.5	50, 100	Tight Tolerance
F	2512	MMB0207	1	700	0.1 to 0.99	1, 2, 5	100	Low Range
					1.0 to 2.21M	1, 2, 5	50, 100	Standard
					20 to 348K	0.25, 0.5	50, 100	Tight Tolerance
н	3610	MMC0310	2	1000	0.1 to 0.99	1, 2, 5	100	Low Range
					1.0 to 2.21M	1, 2, 5	50, 100	Standard

¹Not to exceed $\sqrt{P} \times R$ ²Consult factory for tighter TCR, tolerance, or resistance values.

Environmental Data

Characteristics	Maximum Change	Test Method
Temperature Coefficient	As specified	MIL-R-55342E Par 4.7.9 (-55°C +125°C)
Thermal Shock	±0.5% +0.01Ω	MIL-R-55342E Par 4.7.3 (-65°C +150°C, 5 cycles)
Low Temperature Operation	±0.25% +0.01Ω	MIL-R-55342E Par 4.7.4 (-65°C @ working voltage)
Short Time Overload	$\pm 0.5\%$ +0.01Ω $\pm 1\%$ for R>100KΩ	MIL-R-55342E Par 4.7.5 2.5 x √P x R for 5 seconds
High Temperature Exposure	±0.5% +0.01Ω	MIL-R-55342E Par 4.7.6 (+150°C for 100 hours)
Resistance to Bonding Exposure	±0.25% +0.01Ω	MIL-R-55342E Par 4.7.7 (Reflow soldered to board at 260°C for 10 seconds)
Solderability	95% minimum coverage	MIL-STD-202, Method 208 (245°C for 5 seconds)
Moisture Resistance	±0.5% +0.01Ω	MIL-R-55342E Par 4.7.8 (10 cycles, total 240 hours)
Life Test	±0.5% +0.01Ω	MIL-R-55342E Par 4.7.10 (2000 hours @ 70°C intermittent)
Terminal Adhesion Strength	$\pm 1\% + 0.01\Omega$ no mechanical damage	1200 gram push from underside of mounted chip for 60 seconds
Resistance to Board Bending	$\pm 0.5\%$ +0.01 Ω no mechanical damage	Chip mounted in center of 90mm long board, deflected 5mm so as to exert pull on chip contacts for 10 seconds

General Note

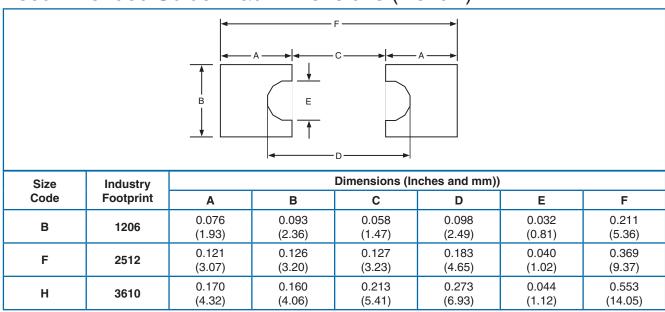


Physical Data

			w			
	Industry		Dimensions (Inches and (mm)			
Size Code	Footprint	Actual Size	L	W	C*	
В	1206	(=)	0.128 ± 0.007 (3.25 ± 0.18)	0.057 ± 0.006 (1.45 ± 0.15)	0.020 ± 0.010 (0.51 ± 0.25)	
F	2512		0.251 ± 0.010 (6.38 ± 0.25)	0.079 ± 0.006 (2.01 ± 0.15)	0.040 ± 0.010 (1.02 ± 0.25)	
Н	3610		0.367 ± 0.010 (9.32 ± 0.25)	0.105 ± 0.006 (2.67 ± 0.15)	0.050 ± 0.010 (1.27 ± 0.25)	

^{*}C dimension is average termination width.

Recommended Solder Pad Dimensions (Reflow):



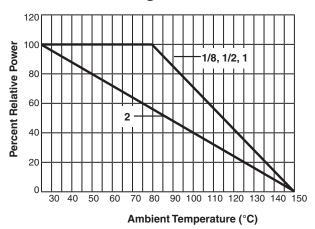


Standard Reel Packaging per EIA-481:

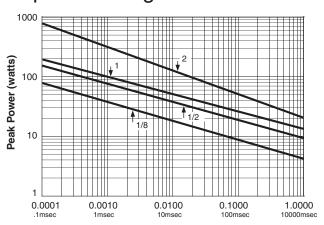
Size Code	Industry Footprint	Reel Diameter*	Quantity Per Reel	Carrier Tape Width	Component Pitch
В	1206	7"	2,500 max.	8mm	4mm
В		13"	10,000 max.	OHIIII	
F	0510	7"	1,500 max.	10,000	4mm
	2512	13″	5,000 max.	12mm	
н	3610	13″	1,500 max.	24mm	4mm

^{*}The 13" reel is considered standard and will be supplied unless otherwise specified.

Power Derating Curve



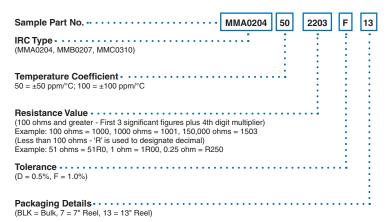
Repetitive Surge Curve



Surge or Pulse Duration (seconds)

Note: Use for repetitive pulses where the average power dissipation is not to exceed the component rating at 70C. Surge handling capacity for low-repetitive surges may be significantly greater than shown above. Contact factory for recommendations.

Ordering Data



Note:

RoHS compliance is noted by inserting "LF" into the part number immediately following the tolerance designator. RoHS compliant metallization is 96.5% Sn / 3% Ag / 0.5% Cu. RoHS-compliant product is NOT backwards compatible to Sn/Pb soldering environments.